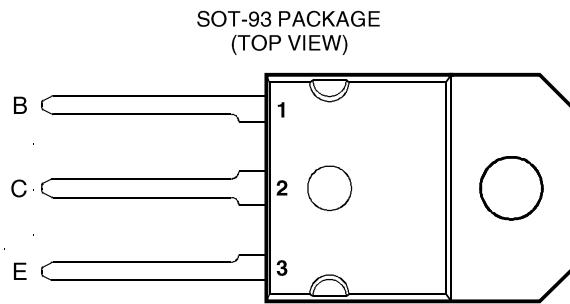


- Rugged Triple-Diffused Planar Construction
- 10 A Continuous Collector Current
- Operating Characteristics Fully Guaranteed at 100°C
- 1000 Volt Blocking Capability
- 125 W at 25°C Case Temperature



Pin 2 is in electrical contact with the mounting base.

absolute maximum ratings at 25°C case temperature (unless otherwise noted)

RATING	SYMBOL	VALUE	UNIT
Collector-base voltage ($I_E = 0$)	V_{CBO}	850 1000	V
Collector-emitter voltage ($V_{BE} = 0$)	V_{CES}	850 1000	V
Collector-emitter voltage ($I_B = 0$)	V_{CEO}	400 450	V
Emitter-base voltage	V_{EBO}	10	V
Continuous collector current	I_C	10	A
Peak collector current (see Note 1)	I_{CM}	15	A
Continuous device dissipation at (or below) 25°C case temperature	P_{tot}	125	W
Operating junction temperature range	T_j	-65 to +150	°C
Storage temperature range	T_{stg}	-65 to +150	°C

NOTE 1: This value applies for $t_p \leq 10$ ms, duty cycle $\leq 2\%$.

TIPL765, TIPL765A NPN SILICON POWER TRANSISTORS

electrical characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS				MIN	TYP	MAX	UNIT
$V_{CEO(sus)}$	Collector-emitter sustaining voltage	$I_C = 100 \text{ mA}$	$L = 25 \text{ mH}$	(see Note 2)	TIPL765 TIPL765A	400 450		V
I_{CES}	Collector-emitter cut-off current	$V_{CE} = 850 \text{ V}$	$V_{BE} = 0$		TIPL765		50	μA
		$V_{CE} = 1000 \text{ V}$	$V_{BE} = 0$		TIPL765A		50	
		$V_{CE} = 850 \text{ V}$	$V_{BE} = 0$	$T_C = 100^\circ\text{C}$	TIPL765		200	
		$V_{CE} = 1000 \text{ V}$	$V_{BE} = 0$	$T_C = 100^\circ\text{C}$	TIPL765A		200	
I_{CEO}	Collector cut-off current	$V_{CE} = 400 \text{ V}$	$I_B = 0$		TIPL765		50	μA
		$V_{CE} = 450 \text{ V}$	$I_B = 0$		TIPL765A		50	
I_{EBO}	Emitter cut-off current	$V_{EB} = 10 \text{ V}$	$I_C = 0$				1	mA
h_{FE}	Forward current transfer ratio	$V_{CE} = 5 \text{ V}$	$I_C = 0.5 \text{ A}$	(see Notes 3 and 4)	15		60	
$V_{CE(sat)}$	Collector-emitter saturation voltage	$I_B = 0.4 \text{ A}$	$I_C = 2 \text{ A}$				0.5	V
		$I_B = 1 \text{ A}$	$I_C = 5 \text{ A}$	(see Notes 3 and 4)			1.0	
		$I_B = 2 \text{ A}$	$I_C = 10 \text{ A}$				2.5	
		$I_B = 2 \text{ A}$	$I_C = 10 \text{ A}$	$T_C = 100^\circ\text{C}$			5.0	
$V_{BE(sat)}$	Base-emitter saturation voltage	$I_B = 0.4 \text{ A}$	$I_C = 2 \text{ A}$				1.1	V
		$I_B = 1 \text{ A}$	$I_C = 5 \text{ A}$	(see Notes 3 and 4)			1.3	
		$I_B = 2 \text{ A}$	$I_C = 10 \text{ A}$				1.7	
		$I_B = 2 \text{ A}$	$I_C = 10 \text{ A}$	$T_C = 100^\circ\text{C}$			1.6	
f_t	Current gain bandwidth product	$V_{CE} = 10 \text{ V}$	$I_C = 0.5 \text{ A}$	$f = 1 \text{ MHz}$		8		MHz
C_{ob}	Output capacitance	$V_{CB} = 20 \text{ V}$	$I_E = 0$	$f = 0.1 \text{ MHz}$		150		pF

NOTES: 2. Inductive loop switching measurement.

3. These parameters must be measured using pulse techniques, $t_p = 300 \mu\text{s}$, duty cycle $\leq 2\%$.

4. These parameters must be measured using voltage-sensing contacts, separate from the current carrying contacts.

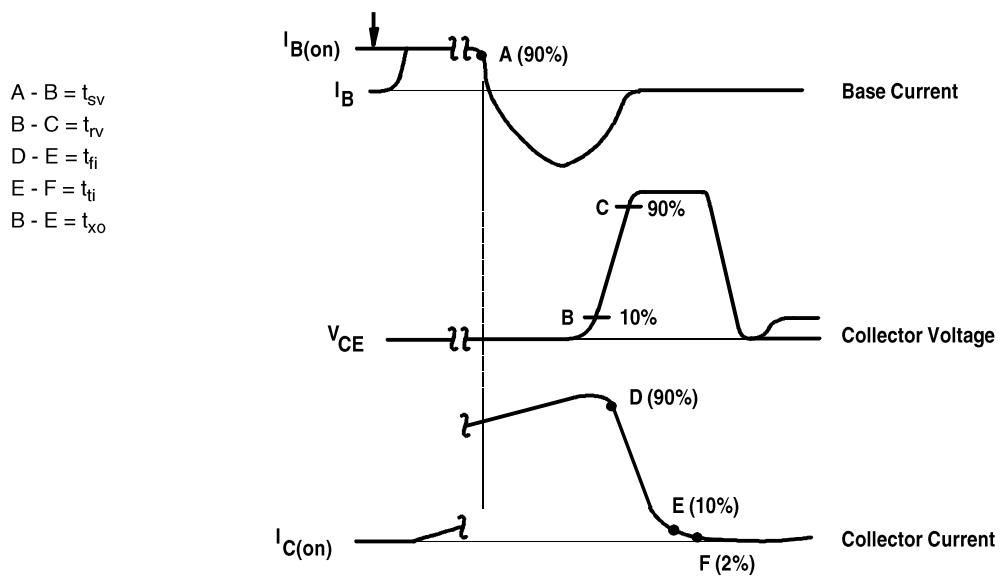
thermal characteristics

PARAMETER	MIN	TYP	MAX	UNIT
$R_{\theta JC}$ Junction to case thermal resistance			1	°C/W

inductive-load-switching characteristics at 25°C case temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS †				MIN	TYP	MAX	UNIT
t_{sv}	$I_C = 10 \text{ A}$ $V_{BE(off)} = -5 \text{ V}$	$I_{B(on)} = 2 \text{ A}$ (see Figures 1 and 2)					2	μs
t_{rv}							300	ns
t_{fi}							200	ns
t_{ti}							50	ns
t_{xo}							400	ns
t_{sv}	$I_C = 10 \text{ A}$ $V_{BE(off)} = -5 \text{ V}$	$I_{B(on)} = 2 \text{ A}$ $T_C = 100^\circ\text{C}$ (see Figures 1 and 2)					3.5	μs
t_{rv}							400	ns
t_{fi}							300	ns
t_{ti}							80	ns
t_{xo}							500	ns

† Voltage and current values shown are nominal; exact values vary slightly with transistor parameters.



NOTES: A. Waveforms are monitored on an oscilloscope with the following characteristics: $t_r < 15$ ns, $R_{in} > 10 \Omega$, $C_{in} < 11.5$ pF.
 B. Resistors must be noninductive types.

Figure 2. Inductive-Load Switching Waveform s

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TYPICAL CHARACTERISTICS

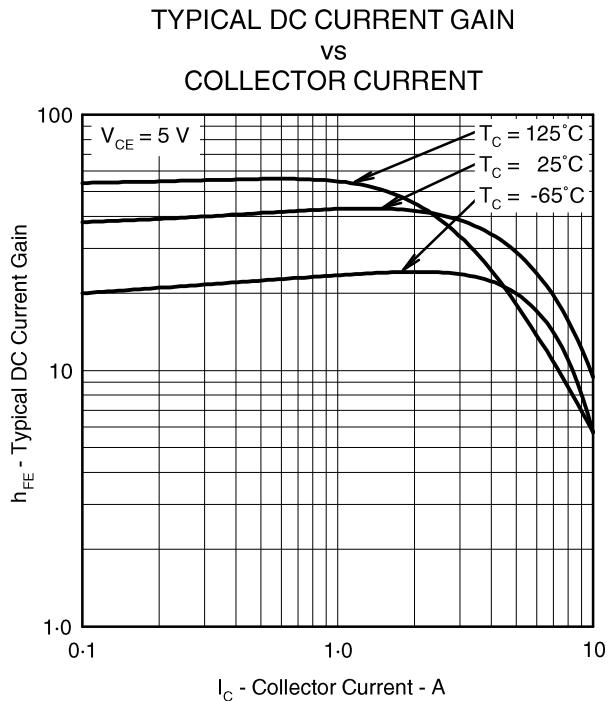


Figure 3.

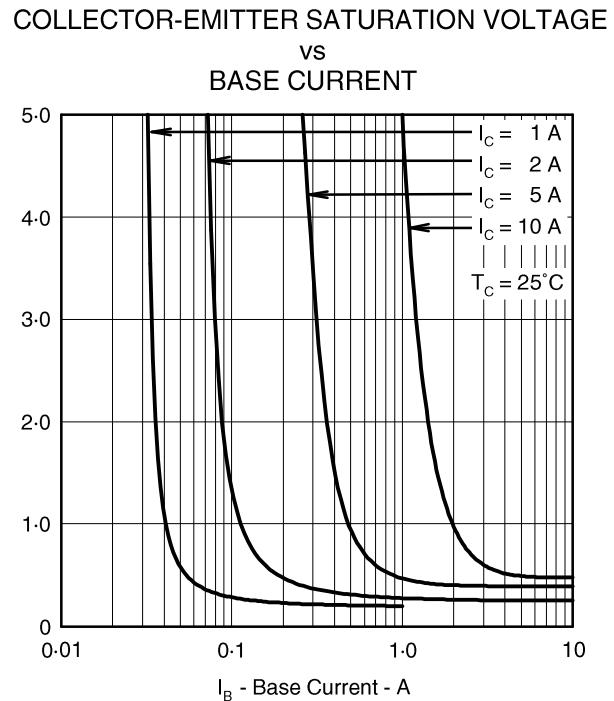


Figure 4.

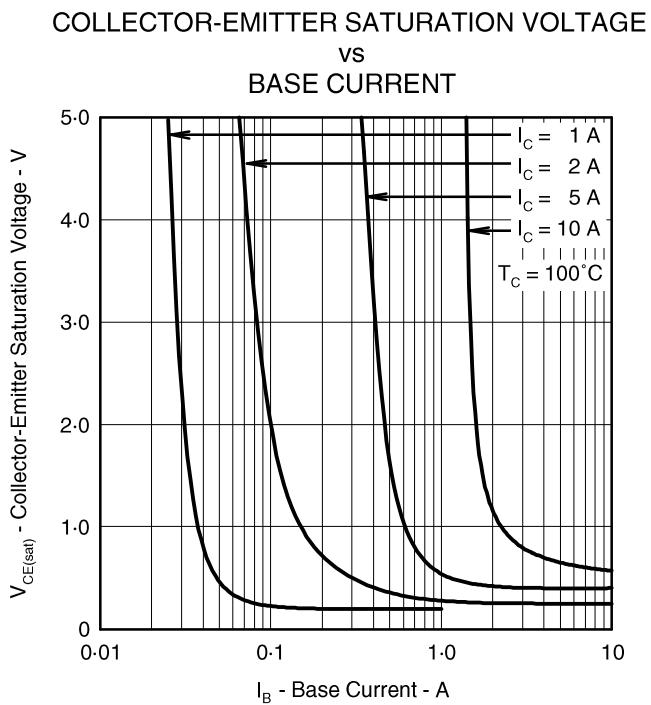


Figure 5.

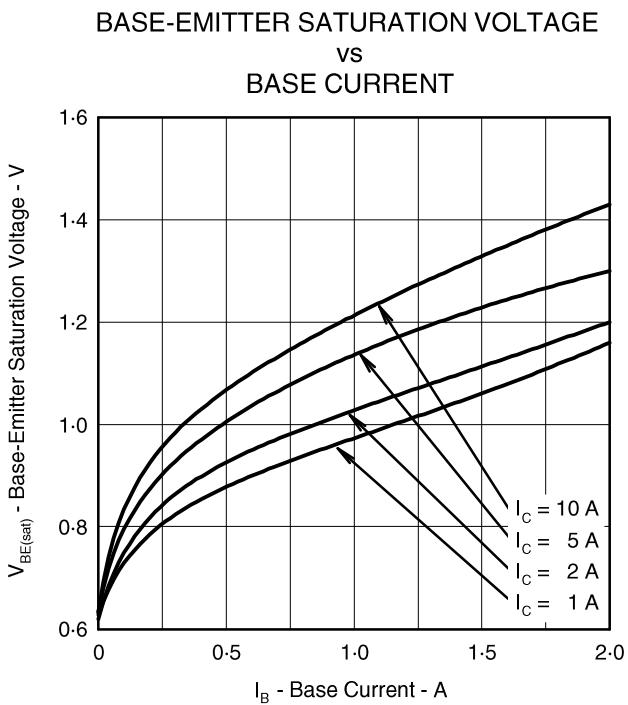


Figure 6.

TYPICAL CHARACTERISTICS

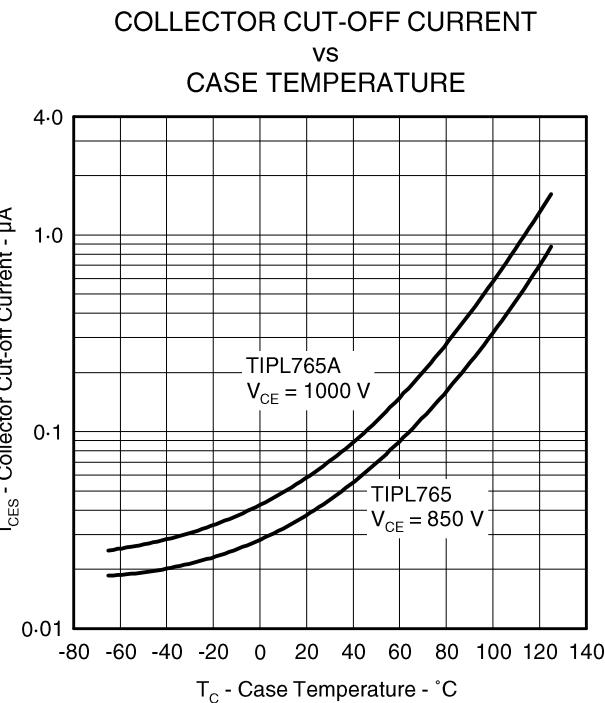


Figure 7.

MAXIMUM SAFE OPERATING REGIONS

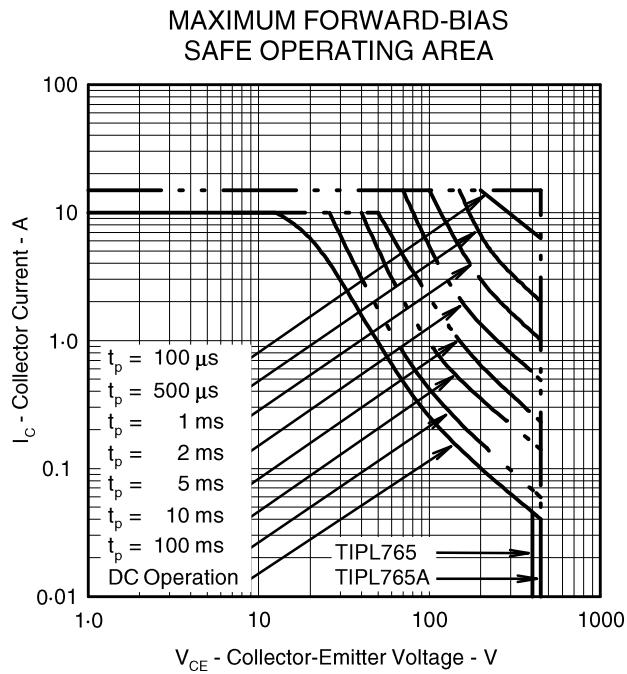


Figure 8.

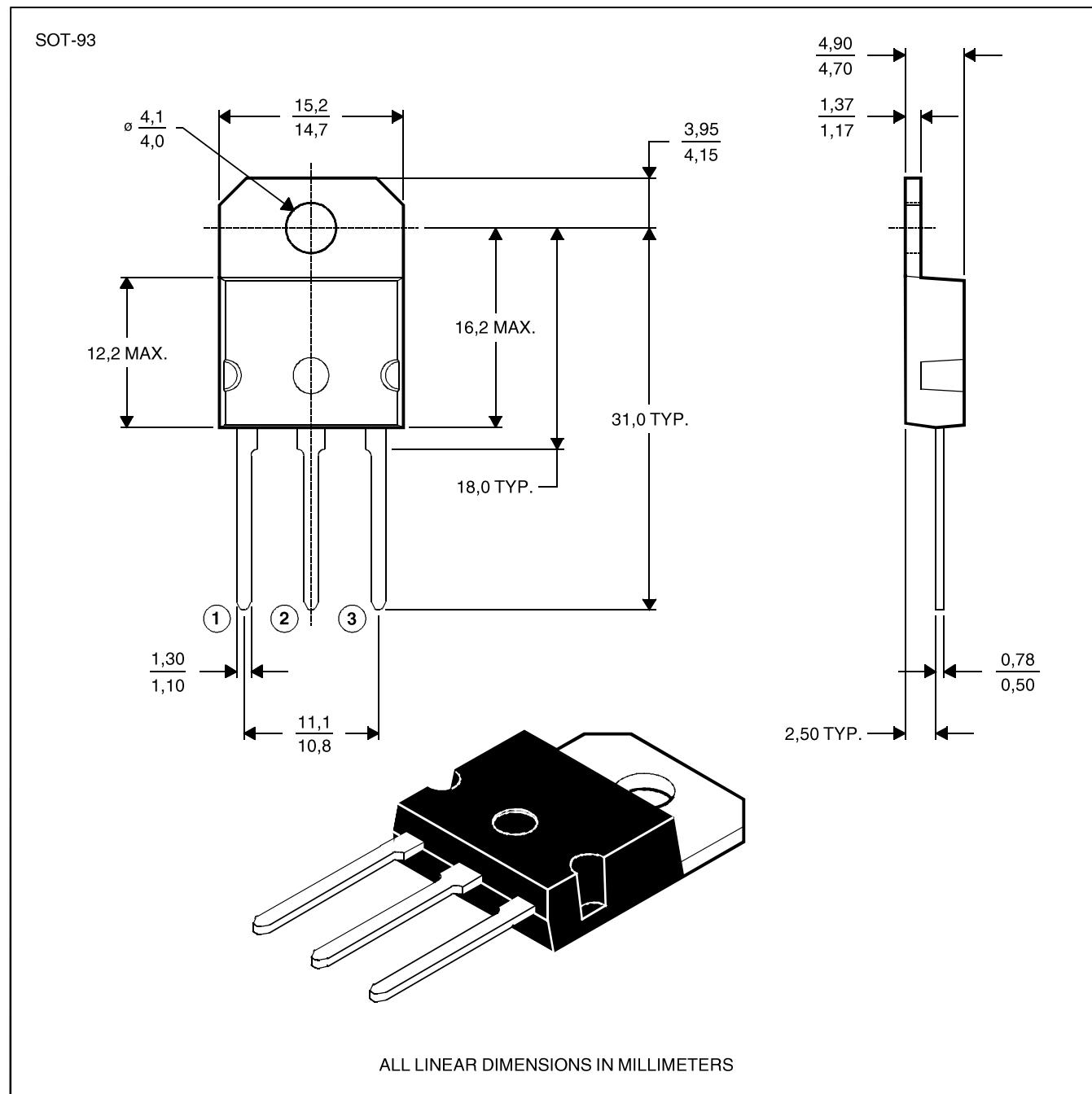
TIPL765, TIPL765A NPN SILICON POWER TRANSISTORS

MECHANICAL DATA

SOT-93

3-pin plastic flange-mount package

This single-in-line package consists of a circuit mounted on a lead frame and encapsulated within a plastic compound. The compound will withstand soldering temperature with no deformation, and circuit performance characteristics will remain stable when operated in high humidity conditions. Leads require no additional cleaning or processing when used in soldered assembly.



NOTE A: The centre pin is in electrical contact with the mounting tab.